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Renesas Electronics website: http://www.renesas.com

April 1<sup>st</sup>, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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## DATA SHEET



# **HETERO JUNCTION FIELD EFFECT TRANSISTOR**

NE3512S02

# C TO Ku BAND SUPER LOW NOISE AMPLIFIER N-CHANNEL HJ-FET

#### **FEATURES**

- Super low noise figure and high associated gain
   NF = 0.35 dB TYP., Ga = 13.5 dB TYP. @ f = 12 GHz
- · Micro-X plastic (S02) package

#### **APPLICATIONS**

- C to Ku-band DBS LNB
- · Other C to Ku-band communication systems

#### **ORDERING INFORMATION**

| Part Number   | Order Number    | Package       | Quantity     | Marking | Supplying Form  |
|---------------|-----------------|---------------|--------------|---------|---|
| NE3512S02-T1C | NE3512S02-T1C-A | S02 (Pb-Free) | 2 kpcs/reel  | С       | • 8 mm wide embossed taping   |
| NE3512S02-T1D | NE3512S02-T1D-A |               | 10 kpcs/reel |         | <ul> <li>Pin 4 (Gate) faces the perforation side<br/>of the tape</li> </ul> |

Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: NE3512S02

#### ABSOLUTE MAXIMUM RATINGS (TA = +25°C)

| Parameter               | Symbol           | Ratings     | Unit |
|-------------------------|------------------|-------------|------|
| Drain to Source Voltage | V <sub>DS</sub>  | 4           | V    |
| Gate to Source Voltage  | V <sub>GS</sub>  | -3          | V    |
| Drain Current           | ΙD               | loss        | mA   |
| Gate Current            | lg               | 100         | μΑ   |
| Total Power Dissipation | Ptot Note        | 165         | mW   |
| Channel Temperature     | Tch              | +125        | °C   |
| Storage Temperature     | T <sub>stg</sub> | -65 to +125 | °C   |

Note Mounted on 1.08 cm<sup>2</sup> × 1.0 mm (t) glass epoxy PCB

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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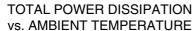
# RECOMMENDED OPERATING CONDITIONS ( $T_A = +25$ °C)

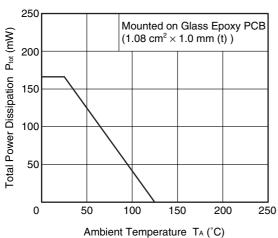
| Parameter               | Symbol | MIN. | TYP. | MAX. | Unit |
|-------------------------|--------|------|------|------|------|
| Drain to Source Voltage | VDS    | 1    | 2    | 3    | V    |
| Drain Current           | lσ     | 5    | 10   | 15   | mA   |
| Input Power             | Pin    | _    | _    | 0    | dBm  |

# ELECTRICAL CHARACTERISTICS (TA = +25°C, unless otherwise specified)

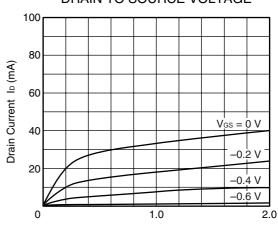
| Parameter                     | Symbol         | Test Conditions   | MIN. | TYP. | MAX. | Unit |
|-------------------------------|----------------|---|------|------|------|------|
| Gate to Source Leak Current   | Igso           | $V_{GS} = -3 V$   | 1    | 0.5  | 10   | μΑ   |
| Saturated Drain Current       | IDSS           | V <sub>DS</sub> = 2 V, V <sub>GS</sub> = 0 V              | 15   | 40   | 70   | mA   |
| Gate to Source Cutoff Voltage | VGS (off)      | $V_{DS} = 2 \text{ V}, I_{D} = 100 \ \mu\text{A}$         | -0.2 | -0.7 | -2.0 | ٧    |
| Transconductance              | g <sub>m</sub> | V <sub>DS</sub> = 2 V, I <sub>D</sub> = 10 mA             | 40   | 55   | _    | mS   |
| Noise Figure                  | NF             | V <sub>DS</sub> = 2 V, I <sub>D</sub> = 10 mA, f = 12 GHz | _    | 0.35 | 0.5  | dB   |
| Associated Gain               | Ga             |   | 12.5 | 13.5 | _    | dB   |

#### TYPICAL CHARACTERISTICS (TA = +25°C, unless otherwise specified)



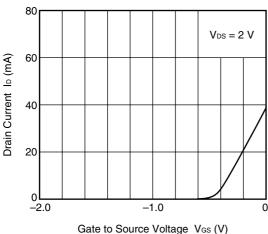


DRAIN CURRENT vs.
DRAIN TO SOURCE VOLTAGE



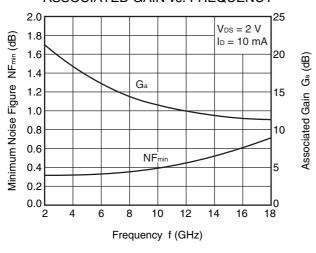
Drain to Source Voltage VDS (V)

# DRAIN CURRENT vs. GATE TO SOURCE VOLTAGE

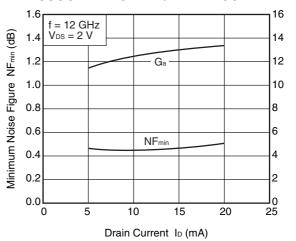


Gate to Source voltage VGS (V)

### MINIMUM NOISE FIGURE, ASSOCIATED GAIN vs. FREQUENCY



MINIMUM NOISE FIGURE, ASSOCIATED GAIN vs. DRAIN CURRENT



**Remark** The graphs indicate nominal characteristics.

NEC NE3512S02

#### **S-PARAMETERS**

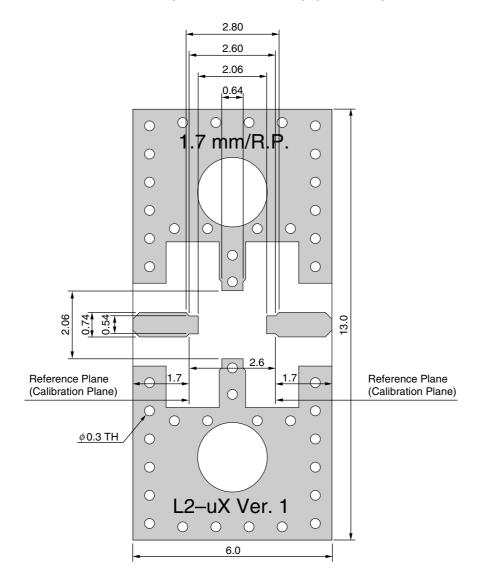
S-parameters/Noise parameters are provided on the NEC Compound Semiconductor Devices Web site in a form (S2P) that enables direct import to a microwave circuit simulator without keyboard input.

Click here to download S-parameters.

 $[\mathsf{RF} \ \mathsf{and} \ \mathsf{Microwave}] \to [\mathsf{Device} \ \mathsf{Parameters}]$ 

URL http://www.ncsd.necel.com/

# RF MEASURING LAYOUT PATTERN (REFERENCE ONLY) (UNIT: mm)



RT/duroid 5880/ROGERS

t = 0.254 mm

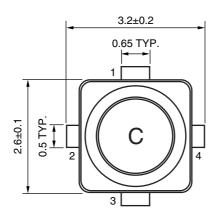
 $\varepsilon r = 2.20$ 

tan delta = 0.0009 @ 10 GHz

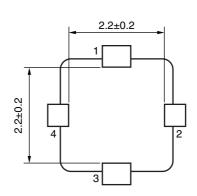
## **PACKAGE DIMENSIONS**

S02 (UNIT: mm)

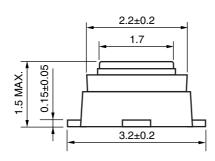
(Top View)



(Bottom View)



(Side View)



## **PIN CONNECTIONS**

- 1. Source
- 2. Drain
- 3. Source
- 4. Gate



#### RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

| Soldering Method | Soldering Conditions  | Condition Symbol  |       |
|------------------|---|---|-------|
| Infrared Reflow  | Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass) | : 260°C or below<br>: 10 seconds or less<br>: 60 seconds or less<br>: 120±30 seconds<br>: 3 times<br>: 0.2%(Wt.) or below | IR260 |
| Partial Heating  | Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)   | : 350°C or below<br>: 3 seconds or less<br>: 0.2%(Wt.) or below   | HS350 |

Data Sheet PG10592EJ01V0DS

Caution Do not use different soldering methods together (except for partial heating).

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M8E 00.4-0110

NEC NE3512S02

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GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

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  - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

#### ▶ For further information, please contact

#### NEC Compound Semiconductor Devices, Ltd. http://www.ncsd.necel.com/

E-mail: salesinfo@ml.ncsd.necel.com (sales and general)

techinfo@ml.ncsd.necel.com (technical)

Sales Division TEL: +81-44-435-1573 FAX: +81-44-435-1579

#### **NEC Compound Semiconductor Devices Hong Kong Limited**

E-mail: ncsd-hk@elhk.nec.com.hk (sales, technical and general)

Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309 Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859 Korea Branch Office TEL: +82-2-558-2120 FAX: +82-2-558-5209

### NEC Electronics (Europe) GmbH http://www.ee.nec.de/

TEL: +49-211-6503-0 FAX: +49-211-6503-1327

#### California Eastern Laboratories, Inc. http://www.cel.com/

TEL: +1-408-988-3500 FAX: +1-408-988-0279